

Title (en)

QUASICRYSTALLINE COMPOUND AND THE USE THEREOF AS A HEAT INSULATING LAYER

Title (de)

QUASIKRISTALLINE VERBINDUNG UND DEREN VERWENDUNG ALS WÄRMEDÄMMSCHICHT

Title (fr)

COMPOSÉ QUASICRISTALLIN ET SON UTILISATION COMME COUCHE D'ISOLATION THERMIQUE

Publication

EP 1996795 A2 20081203 (DE)

Application

EP 07727208 A 20070322

Priority

- EP 2007052732 W 20070322
- EP 06006053 A 20060323
- EP 07727208 A 20070322

Abstract (en)

[origin: EP1837484A2] Compounds of formula: Al wCo xM yare new. M is Ni and/or Cr and at least 30 mass% of the compound has a quasi-crystalline structure. W = 70 - 76 and w + x + y = 100. Independent claims are included for: (A) coatings made from or containing the compounds; (B) coating systems containing a coating made from the compounds; (C) multi-layer coating systems containing two or more of the coating systems; (D) use of the compounds as heat-insulating coatings for components subjected to high temperature, especially turbine steam inlets (333) and blades (357); and (E) use of compounds containing aluminum and manganese, at least 30 mass% of the compound having a quasi-crystalline structure, for the same purpose.

IPC 8 full level

F01D 5/28 (2006.01); **C22C 21/00** (2006.01); **C23C 4/08** (2006.01); **C23C 28/00** (2006.01); **C23C 28/02** (2006.01); **C23C 30/00** (2006.01)

CPC (source: EP US)

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